

years and the rate of duty set forth opposite each such year shall be inserted effective for goods of Korea in lieu thereof:

2017	1%
2018	0.7%
2019	0.5%
2020	0.2%
2021	Free

15. The following new additional U.S. note 14 is inserted in numerical sequence in chapter 85:

"14. For purposes of this chapter, the expression "goods described in additional U.S. note 14 to this chapter" are multi-component integrated circuits (MCOs), comprising a combination of one or more monolithic, hybrid, and/or multi-chip integrated circuits with at least one of the following components: silicon-based sensors, actuators, oscillators, resonators or combinations thereof, or components performing the functions of articles classifiable under heading 8532, 8533, 8541, or inductors classifiable under heading 8504, formed to all intents and purposes indivisibly into a single body like an integrated circuit, as a component of a kind used for assembly onto a printed circuit board (PCB) or other carrier, through the connecting of pins, leads, balls, lands, bumps, or pads.

For the purpose of this definition :

1. "Components" may be discrete, manufactured independently then assembled onto the rest of the MCO, or integrated into other components.
2. "Silicon based" means built on a silicon substrate, or made of silicon materials, or manufactured onto integrated circuit die.
3. (a) "Silicon based sensors" consist of microelectronic and/or mechanical structures that are created in the mass or on the surface of a semiconductor and that have the function of detecting physical or chemical quantities and transducing these into electric signals, caused by resulting variations in electric properties or displacement of a mechanical structure. "Physical or chemical quantities" relates to real world phenomena, such as pressure, acoustic waves, acceleration, vibration, movement, orientation, strain, magnetic field strength, electric field strength, light, radioactivity, humidity, flow, chemicals concentration, etc.
- (b) "Silicon based actuators" consist of microelectronic and mechanical structures that are created in the mass or on the surface of a semiconductor and that have the function of converting electrical signals into physical movement.
- (c) "Silicon based resonators" are components that consist of microelectronic and/or mechanical structures that are created in the mass or on the surface of a semiconductor and have the function of generating a mechanical or electrical oscillation of a predefined frequency that depends on the physical geometry of these structures in response to an external input.

- (d) "Silicon based oscillators" are active components that consist of microelectronic and/or mechanical structures that are created in the mass or on the surface of a semiconductor and that have the function of generating a mechanical or electrical oscillation of a predefined frequency that depends on the physical geometry of these structures."

16. Subheadings 8504.90.20 through 8504.90.95 are deleted and the following new provisions are inserted in lieu thereof:

[8504	:Electrical transformers, ...]	:	:	:
[8504.90	: Parts:]	:	:	:
"8504.90.01	: Goods described in additional U.S. note 14 to	:	:	:
:	: this chapter.....	:Free	:	:35%
:	:	:	:	:
:	: Other:	:	:	:
:	: Of power supplies for automatic data	:	:	:
:	: processing machines or units thereof of	:	:	:
:	: heading 8471; of power supplies for goods	:	:	:
:	: of subheading 8443.31 or 8443.32; of power	:	:	:
:	: supplies for monitors of subheading 8528.41	:	:	:
:	: or 8528.51 or projectors of subheading	:	:	:
:	: 8528.61:	:	:	:
8504.90.20	: Printed circuit assemblies.....	:Free	:	:35%
:	:	:	:	:
8504.90.41	: Other.....	:Free	:	:35%
:	: Other:	:	:	:
:	: Printed circuit assemblies:	:	:	:
8504.90.65	: Of the goods of subheading	:	:	:
:	: 8504.40 or 8504.50 for	:	:	:
:	: telecommunication apparatus.....	:Free	:	:35%
:	:	:	:	:
8504.90.75	: Other.....	:[See an-	:Free (A,AU,B,	:35%
:	:	: nex II]	: BH,CA,CL,CO,	:
:	:	:	: E,IL,JO,KR,MA,	:
:	:	:	: MX,OM,P,PA,	:
:	:	:	: PE,SG)	:
8504.90.96	: Other.....	:[See an-	:Free (A,AU,B,	:35%"
:	:	: nex II]	: BH,CA,CL,CO,	:
:	:	:	: E,IL,JO,KR,MA,	:
:	:	:	: MX,OM,P,PA,	:
:	:	:	: PE,SG)	:

17. Subheading 8505.90.80 is deleted and the following new provisions are inserted in lieu thereof: